



**CAREER
DEVELOPMENT CELL**
Where aspirations meet opportunities

STUDENT HANDBOOK FOR INTERNSHIP & PLACEMENT

2025-2026





Preface

Introduction

Placements and internships mark a turning point in a student's life. The uncertainty of passing the online test, the blurry demarcation of syllabus to prepare for assessments, the fear of missing out any information that may be known to all but you, the daunting interviews – the anxiety of all that is unknown is enough to make anyone quake in their shoes.

To tackle that very anxiety, the Career Development Cell presents the '**Student Handbook for Internship & Placement (SHIP)**'. The SHIP is to make your placement and internship season a smooth sail. The following pages enlist the companies that visited IIT BHUBANESWAR in session 2024–25 for placement and internships, along with how many students they recruited, their eligibility criteria, their assessment pattern, etc. SHIP will demystify the companies for you. Now, it's your turn to show your mettle. All the best!

DO'S

- Attend pre-placement talks and research the company well and prepare a couple of questions to ask the panel for brownie points.
- Dress appropriately. Make sure your first impression is of a have-it-all-together person.
- Make sure to know every inch of information you added in your resume thoroughly.
- Arrive on time to avoid any last-minute hiccups.
- Be polite and courteous in and outside the interview room. Maintain a respectful eye contact.

DON'TS

- Don't cheat in your online assessments.
- Don't lie on your resume. Lies to cover up that one lie are easily discernible in the interviews.
- Don't look nervous. That might make you look incompetent.
- Don't ramble. Keep your answers precise. Prepare of expected questions to avoid that.
- Don't criticize yourself or oversell yourself. Know the optimum point where your weakness becomes just another way for you to grow.

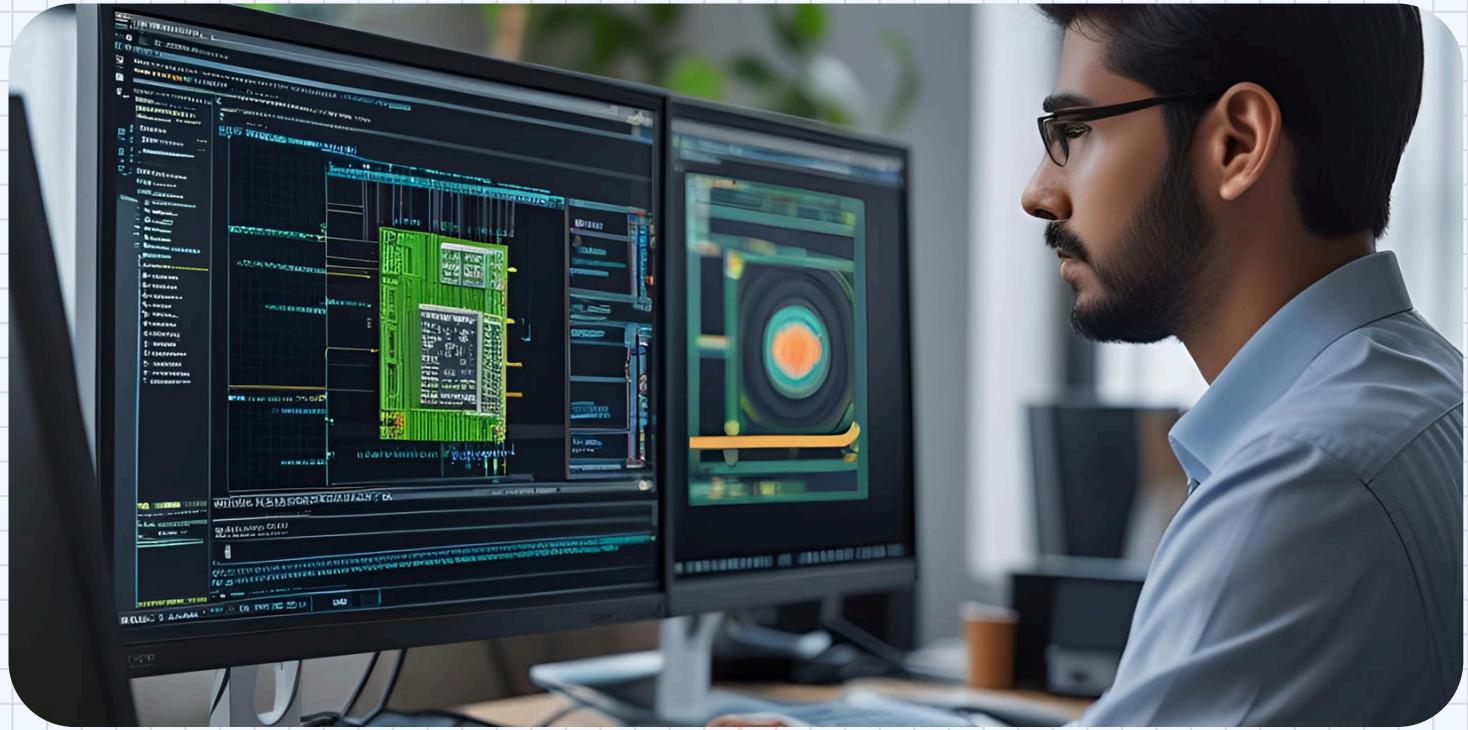
CIVIL ROLES



Preparation

- 1. Master Core Civil Engineering Subjects:** Focus on foundational courses. A strong understanding of those principles is crucial. Be especially well-versed in concepts from the **ICCM** course, as basic questions from this area are frequently asked. Many organizations, including those like BIS, often consider CGPA as a primary screening criterion.
- 2. Gain Practical Experience :** interviewers also ask about the projects or research done on core topics and concepts.
- 3. Know Civil Related Softwares:** Proficiency in essential civil engineering software such as **AutoCAD, STAAD.Pro, ETABS** etc. Try to build a project or have a certification in the same.
- 4. Highlight Communication and Teamwork Abilities:** Emphasize any experience you have working in teams, communicating technical information clearly, and managing project timelines. Strong interpersonal skills are vital for success in this field.

ECE ROLES



Preparation

- 1. Master your core courses:** A strong foundation in subjects like Digital Electronics (DEC), Introduction to Electronics (IE), Network Theory (NT), and Signals & Systems (SS) is fundamental for all ECE roles.
- 2. For Analog roles, focus on circuit design:** Develop a strong understanding of circuits involving op-amps and device-level components (MOS, BJT), as these are frequently tested (e.g., in *Lenovo* interviews).
- 3. For Digital roles, solidify your DEC knowledge:** Confidence in Digital Electronics Concepts (DEC) is crucial and often assessed (e.g., in *Nvidia* interviews).
- 4. Start learning MPMC and Verilog basics:** Familiarise yourself with the fundamentals of Microprocessors and Microcontrollers (MPMC) and hardware description languages like Verilog as these are often expected (e.g., in *Lenovo* interviews). Also try to build a project in it.
- 5. Utilize Resources :**

For architecture: [youtube](#) [youtube](#)

For MPMC : [youtube](#) [youtube](#)

For Verilog : [youtube](#)

For DEC : [Drive](#)

ELECTRICAL ROLES



Preparation

1. Understand and Analyze the main areas :

- **Motors** - Induction , Synchronous, DC and the ones which are newer like BLDC (Know their construction, working, advantages, and real-life applications).
- **Transformers** - Core and winding materials Types: Step-up, step-down, auto-transformers, isolation transformers Efficiency, losses, and cooling methods (Practical applications and conceptual understanding are key).
- **Power Electronics** - Gain clarity on: AC-DC (Rectifiers), DC-DC (Buck, Boost, Buck-Boost), DC-AC (Inverters) AC-AC (Cycloconverters, AC Voltage Controllers).
- **Electrical Power Transmission and Distribution**- Types of Cables: Overhead (ACSR, AAAC), Underground (XLPE, PILC) (Real-world knowledge of cable types and safety practices is often tested).

2. Prepare for interviews -

- Emphasis on theoretical analysis and system-level understanding.
- Fundamentals can be built using Network Theory and Electrical Technology.
- Focus on interview-relevant applications, not just theory. Practice numerical and work on small simulations (e.g., MATLAB, PSIM).

MECHANICAL ROLES



Preparation

1. **Know your core courses well:** Second-year courses form the backbone of Mechanical Engineering. A solid grasp of these fundamentals is crucial for future academics and projects.
2. **Take up projects early:** Engage in projects through faculty guidance or competitions like AAKRUTI or SAE. They provide valuable practical experience and boost your profile.
3. **Be honest when choosing projects:** If a suggested project doesn't interest you, express it respectfully and ask for alternatives. Don't miss out on good opportunities just because the first option didn't click.
4. **Avoid taking on too much:** Stick to one project at a time alongside academics. Juggling multiple commitments can lead to burnout, especially before placements.
5. **Apply for research internships (cold mailing):** Reach out to professors for research opportunities. Even if you don't land one, the experience helps build skills and prepares you for future academic pursuits.
6. **Stay open to all subjects:** Don't dismiss subjects based on classroom experience. Real interest often develops when you explore them independently.
7. **Make labs count:** Ask questions in labs and engage actively. Practical skills often make a big difference during placements.

META ROLES



Preparation

- 1. Be well-versed in fundamentals:** Thermodynamics and physical metallurgy (especially dislocations and their types) are frequently asked in interviews.
- 2. Know your projects in depth:** If you've done any project work, be prepared to explain every aspect clearly and confidently.
- 3. Revise the iron-carbon diagram:** It's a simple yet commonly overlooked topic—interviewers expect you to know it well.
- 4. Research the company:** Understand the products, services, and recent developments of the company you're interviewing with.
- 5. Balance your CV content:** Include both academic achievements and extracurriculars to prepare for HR interviews.
- 6. Adapt to company-specific needs:** Some technical areas or questions may vary depending on the company—be flexible and do your homework.

DATA SCI/ML ROLES



Preparation

Practice, practice, practice.

There's a chance you might encounter similar questions:

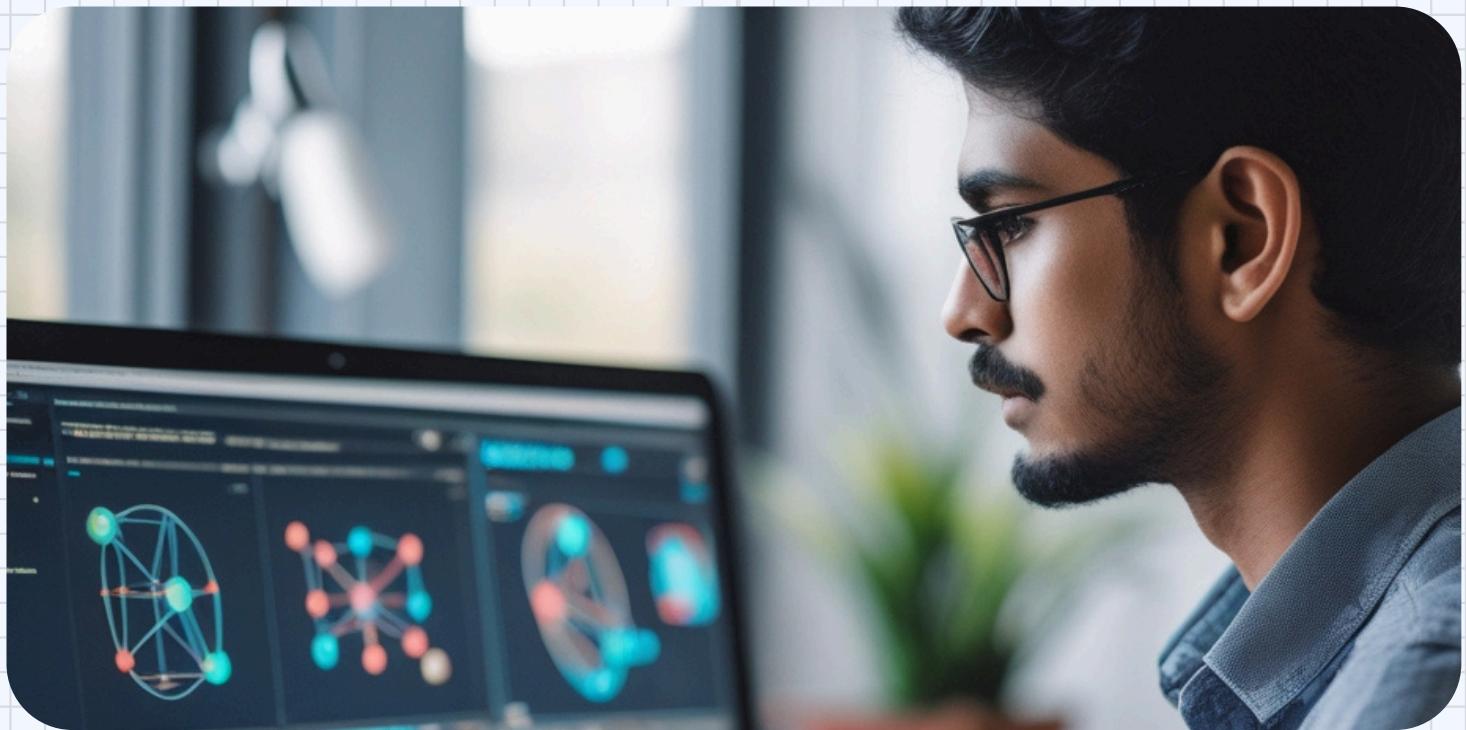
- Solve LeetCode DSA questions
- Practice on Geeks4Geeks
- Add your solution to LeetCode
- Contribute to Numpy, Pandas and Scikit-Learn libraries.

Coursera courses on ML, DSA, AI, Deep Learning

- Course by Andrew NG, Stanford University

Projects: Internship and/or Inter IIT Tech Meet problem statements

SDE ROLES



Preparation

- 1. Build strong problem-solving skills:** Regularly practice on platforms like LeetCode and consistently participate in Codeforces contests. Make sure to upsolve problems to reinforce learning.
- 2. Learn Object-Oriented Programming (OOP):** A solid understanding of OOP principles is fundamental for most SDE roles, regardless of the programming language used.
- 3. For those already into development:** Focus on creating at least one substantial project in your area of interest. A well-built project reflects both technical competence and initiative.
- 4. For those focused on CP but not doing development:** While competitive programming strengthens your algorithmic thinking, it is equally important to demonstrate practical application skills through a project. Consider building something involving OOP, file handling, multithreading, sockets, or a console-based interface.
- 5. For those new to both CP and development:** It is essential to start building skills in at least one of the two areas. SDE roles typically require demonstrable experience in either development or problem-solving.
- 6. Choose a direction and stay consistent:** Whether you pursue development, CP, or a balanced mix of both, commit to your path with focus and consistency. Depth in a chosen area often outweighs shallow experience in many.

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Campus Internships 2024-25

Internship

Job title: Full stack engineering, blockchain, DeFi, and AI

Job Desc:

https://drive.google.com/file/d/1KaguNy4sWwMnwcHKFcZ9kYXcwqOb5ZLI/view?usp=drive_link

Stipend: INR 10,000

CGPA Cutoff: 7.00

Branches: B.Tech/DD (All Branches)

No. of Interns taken: 2

About the Interview

1. Resume Shortlisting
2. Assignment
3. Interview

Internship

Job title: Data Science Research Intern

Job Desc:

https://drive.google.com/file/d/1yGXFkM_zPX6N8nUwjLwD08D2_dp0M0Ye/view?usp=drive_link

Stipend: INR 30,000/-

CGPA Cutoff: 8.00

Branches: B.Tech in CS/ECE/EE/ME & Dual Degree in CS/EE/ME

No. of Interns taken: 1

About the Interview

Skills

The Intern must have very good understanding on mathematical modelling, statistical analytics/inferences and applied statistics to analyze historical time series or telemetry data.

- Should have strong hands on knowledge on Python/R/MATLAB for mathematical modelling of data and implement appropriate machine learning algorithms.

Internship

Job title: Advance Application Engineering Intern

Job Desc:

https://drive.google.com/file/d/1Fq-KKhIsh-07Upb0_510tmeB5omxkrU1/view?usp=drive_link

Stipend: INR 50,000

CGPA Cutoff: 7.00

Branches: B.Tech (All Branches)

No. of Interns taken: 3

About the Interview

Procedure

- 1.C & T and Coding Assessment(On campus- Physical Mode)
- 2.Communication Assessment(Virtual)
- 3.Interviews (Virtual)

Internship

Job title: Research AI Intern

Job Desc:

https://drive.google.com/file/d/1WiRZVTpBifaX3YMvnPJ0BgR3-c0jAU8/view?usp=drive_link

Stipend: INR 20,000/-

Eligibility: Pre-final year students

Branches: ALL

No. of Interns taken: 2

About the Interview

Procedure

- Resume Shortlisting
- Virtual Interviews

Skills

- Prior experience in Machine Learning or AI is mandatory. Students must have relevant projects or certifications in ML/AI.

Internship

Job title: Intern

Job Desc:

https://drive.google.com/file/d/1VpmOgkKCK8P9UG9iVM4C8WTkiVLZgAc4/view?usp=drive_link

Stipend: INR 20,000/- per Month

CGPA Cutoff: 7.50

Branches: (CE/EE)

No. of Interns taken: 16

About the Interview

Procedure

1. Applications will be sought for twice the number of interns actually required at each BO for each discipline, ensuring an adequate selection pool.
2. These applications will be distributed / divided equally among the mapped institutes, ensuring that all MOU institutes have an equal opportunity to provide interns to the BOs.
3. The selection of the actual no of interns will be on CGPA basis from the applications received for each discipline

Internship

Job title: Software Engineering Intern

Stipend: Bachelors- INR 98,000

Masters- INR 1,21,300

CGPA Cutoff: 7.00

Branches: All Branches

No. of Interns taken: 2

About the Interview

Procedure

1. OT: The test will consist of Aptitude Based MCQs and Programming Questions.
2. Interview: Technical, HR

Internship

Job title: Technological Development Intern

Job Desc:

usp=drive_linkhttps://drive.google.com/file/d/1OiwsmeejVhm3-3RuLVHwA_YoGS4ueepe/view?usp=sharing

Stipend: Rs. 1,50,000/- a month + Benefits

CGPA Cutoff: 7.00 for CS, 8.00 for ECE/EE

Branches: Circuital

No. of Interns taken: 2

About the Interview

Procedure

1. Online Test: DSA (Python, C++); Basic OS; Computer fundamentals; OOPS
 2. Round 1 interview (On campus): 2 DSA questions to be solved in 1 hour
 3. Round 2 interview (On campus): Exhaustive comprehensive technical questions on DSA, projects undertaken and the technical challenges faced
-
- Your thought process for arriving at a solution matters just as much as the solution.

Internship

Job title: Intern Engineer-AI/ML

Job Desc:

https://drive.google.com/file/d/1cI3TW_qE8FQZ1cakJDc57JpC7gA322aT/view?usp=drive_link

Stipend: Rs. 50,000/- a month

CGPA Cutoff: 7.00

Branches: All Branches

No. of Interns taken: 2

About the Interview

1. Resume Shortlisting
2. Online Test
3. Interviews



Google

Internship

Job title: Software Engineering Intern

Job Desc:

https://drive.google.com/file/d/1MiZ4L0wejHoME6rnAqeAt-2Pw_9vZexv/view?usp=drive_link

Stipend: INR 123,333 /month

CGPA Cutoff: 7.00

Branches: B.Tech in CS/EC/EE
Dual Degree in CS/EE

No. of Interns taken: 10

About the Interview

Procedure

1. Shortlisting through resumes
2. A technical 60-minute Google Online Challenge
3. 3-4 technical interviews of 45 minutes each

Skills

1. Experience in systems software or algorithms.
2. Excellent implementation skills (C++, Java, Python).
3. Knowledge of Unix/Linux or Windows environments and APIs.
4. Familiarity with TCP/IP and network programming.



Internship

Job title: Intern – AI Developer

Job Desc:

https://drive.google.com/file/d/16wAXKaHSk0T9WLnwcbyGwyLJs3DyWkgP/view?usp=drive_link

Stipend: Rs. 15,000/- + Accommodation

CGPA Cutoff: 6.50

Branches: Pre-final year students of all branches

No. of Interns taken: 1

About the Interview

1. Resume Shortlisting
2. Online Test
3. Interview



Internship

Job title: Marketing Analyst, Full Stack Software Engineer, Mobile App Developer, AI/ML Engineer

Job Desc:

https://drive.google.com/drive/folders/1YIETGCdZx2lINB5W0ViaoLgeRZNWXvvH?usp=drive_link

Stipend: INR 40,000 per month

CGPA Cutoff: 7.00

Branches: All

No. of Interns taken: 4

About the Interview

- 1.Resume Shortlisting
- 2.Assignments
- 3.Interview

Internship

Job title: Graduate Engineer Trainee (GET) - Intern

Stipend: 25,000 INR per month

CGPA Cutoff: 6.50

Branches: [EE/ME/MME]

No. of Interns taken: 10

About the Interview

Procedure

- Domain Knowledge Test and Aptitude Test
- Extempore/GD
- Personal Interview

Internship

Job title: Hardware Engineering Internship

Job Desc:

https://drive.google.com/file/d/1w7V4eMe6RQ4ocih9H93g6dvnBLEjjEgr/view?usp=drive_link

Stipend: INR 33,000

Eligibility: 3rd year B.tech students

Branches: ECE

No. of Interns taken: 2

About the Interview

Key Responsibilities

1. Assist in designing and testing servers, electrical systems, and hardware circuits.
2. Perform troubleshooting and validation to ensure functionality and compliance with design specifications.
3. Collaborate with teams on project objectives and technical documentation.
4. Support prototype development and product testing

Internship

Job title: Software Development Engineering Intern

Job Desc:

https://drive.google.com/file/d/1ia9tcB1tzlviXcfb6b8btMlqiерDqFkU/view?usp=drive_link

Stipend: INR 100,000

CGPA Cutoff: 6.00

Branches: B.Tech /DD(All Branches)

No. of Interns taken: 2

About the Interview

Procedure

1. Coding Assessment(On campus-Physical Mode)
2. Interviews

Internship

Job title: CIO Office Intern

Job Desc:

https://drive.google.com/file/d/11gthCA9UMXEVleoVSHMa h3B5NzrCnBFk/view?usp=drive_link

Stipend: INR 18,000

CGPA Cutoff: 6.00

Branches: ALL

No. of Interns taken: 1

About the Interview

Procedure

- Intern will be given a task.
- Your thought process for arriving at a solution matters just as much as the solution.

Nvidia

Internship

Job title: Hardware Engineering Intern; System Software Engineering Intern (Girls Only)

Job Desc:

https://drive.google.com/file/d/1SQDAC_zOHheMk-JT_yMIIIX1CFlo5rH7/view?usp=drive_link

Stipend: INR 75,000 (Hardware Engineering Intern); INR 80,000 (System Software Engineering Intern)

CGPA Cutoff: 8.00

Branches: CS/ECE/EE (all prefinal year students)

No. of Interns taken: 2 + 1

About the Interview

Procedure:

1. Assessment
2. Personal Interview

.

Internship

Job title: Management Trainee

Stipend: INR 40,000 per month

CGPA Cutoff: 6.00

Branches: ME, EE, MME (B. Tech)

No. of Interns taken: 6

About the Interview

Procedure

1. There will be a screening process conducted by Reliance
2. Shortlisted students, post screening will get a link from Unstop to complete the application process.
3. Written Assessment (Online):
 - a. Aptitude Test
 - b. Subject Matter Test
4. The Test will be of 90 Min. in offline Mode. There will also be an AI proctoring for the test.
5. Those selected will sit for personal Interview (Technical + HR)

Internship

Job title: Backend Software Engineering Intern

Job Desc:

https://drive.google.com/file/d/1dUpswOPE7FseUav9rWZTKXarN0EK8DIW/view?usp=drive_link

Stipend: 1,00,000 INR per month

CGPA Cutoff: 7.00

Branches: [CS/ECE/EE/ME/CE/MME]

No. of Interns taken: 5

About the Interview

Procedure

1. Resume Shortlisting
2. Online Testing
3. Personal Interview

Internship

Job title: R&D Intern

Job Desc: https://drive.google.com/file/d/1Ch-Lw3KJvHNKkcaqgtQPahWQml_Y3u9B/view?usp=drive_link

Stipend: INR 50,000+ Benefits

CGPA Cutoff: 7.50

Branches: CS/ECE (all prefinal year students only)

No. of Interns taken: 2

About the Interview

Skills Required:

- Proficiency in C/C++, C# and Java
- Knowledge of agile or iterative software development life cycle
- Familiarity with Android development
- Design and problem solving skills
- Strong understanding of object-oriented software development
- Strong written and verbal communication skills



Internship

Job title: IT Intern

Stipend: ₹ 75,000

CGPA Cutoff: 6.00

Branches: B.Tech / DD (All Branches)

No. of Interns taken: 1

About the Interview

Procedure

1. Resume Shortlisting
2. Assignment (Project)
3. GD/Interview (technical)
4. HR Interview

Tata Steel

Internship

Job title: Technical Summer Intern

Job Desc:

https://drive.google.com/file/d/1yC9bMazLvu91KIIwKg0XLW0R006N-ICp/view?usp=drive_link

Stipend: Rs. 40000

CGPA Cutoff: 7.00

Branches: ECE/EE/ME/MM(B.Tech)

No. of Interns taken: 6

About the Interview

Procedure

1.Assessment

2.Interview

Vamshi Gudavarthi (Alumni)

Internship

Job title: Software Engineering Intern

Stipend: Rs. 50000

CGPA Cutoff: 7.00

Branches: All Branches (B.Tech and Dual Degree)

No. of Interns taken: 1

About the Interview

Procedure

1. Individual Task: pick an idea of your choice and describe how you would visualize it using a graphics framework of their preference.
2. Team task (2 people each): take any complex topic – like how a computer processor or an FPGA works – and break them down using a first-principles approach through animation. The goal is to make it accessible, even for someone without a deep technical background, like a journalist.
3. Interview

Internship

Job title: STEM Researcher and Content Developer

Job Desc:

https://drive.google.com/file/d/1IPC0LkdYvjf61uvkvoheldicW_loBLOF/view?usp=drive_link

Stipend: Rs. 10,500

CGPA Cutoff: 6.00

Branches: CS/ECE/EE/ME (B.Tech and DD)

No. of Interns taken: 2

About the Interview

Skills Required:

- Proficiency in STEM concepts
- Creative mindset for project development
- Strong research and analytical abilities.

Zscaler

Internship

Job title: Intern - Software Development

Stipend: INR 75,000/- per month

CGPA Cutoff: 7.00 (No Active Backlogs or Arrears)

Branches: Pre-Final year CS/EC/EE students

No. of Interns taken: 2

About the Interview

Procedure

1. Online Assessment -> Pre-Placement Talk -> 2-3 Interviews
2. Virtual (Online, over Zoom / Google Meet)

Skills

- Proficiency in coding language C, C++, Java, Python



Campus Placements 2024-25



Placement

Job title: AI Analyst/ Protocol Analyst

CTC: INR 15 LPA

CGPA Cutoff: 7.00

Branches: All

No. of students taken: 1

About the Interview

Procedure

1. Applications will be sought for twice the number of interns actually required at each
 2. BO for each discipline, ensuring an adequate selection pool.
 3. These applications will be distributed / divided equally among the mapped institutes,
 4. ensuring that all MOU institutes have an equal opportunity to provide interns to the BOs.
1. The selection of the actual no of interns will be on CGPA basis from the applications received
 2. for each discipline

Placement

Job title: AI Analyst/ Protocol Analyst

CTC: INR 15 LPA

CGPA Cutoff: 7.00

Branches: All

No. of students taken: 1

About the Interview

Procedure

1. Applications will be sought for twice the number of interns actually required at each
 2. BO for each discipline, ensuring an adequate selection pool.
 3. These applications will be distributed / divided equally among the mapped institutes,
 4. ensuring that all MOU institutes have an equal opportunity to provide interns to the BOs.
1. The selection of the actual no of interns will be on CGPA basis from the applications received
 2. for each discipline

Placement

Job title: Digital Consultant / Business Consultant

CTC: JPY 8,132,928 (for both roles)

CGPA Cutoff: Nil

Branches: All

No. of students taken: 3 + 1 (as per the roles respectively)

About the Interview

Procedure

- 1.PPT
- 2.OT
- 3.Interview

Accordion / Merilytics



Placement

Job title: Business Analyst / Data Engineer

CTC: INR 10 LPA (for both roles)

CGPA Cutoff: 6.50

Branches: All B. Tech and Dual Degree students

No. of students taken: 5 + 2 (as per the roles respectively)

About the Interview

Procedure

1. 30-40 mins Online Test to be conducted in classrooms under the invigilation of placement tea
2. Virtual Interview

Placement

Job title: Design Engineer

Job Description:

https://docs.google.com/document/d/1VApSBJdSfvB3fXx9CegF4gU4KKc_hdkMIJZtbHkY2yM/edit?tab=t.0

CTC: INR 15 LPA

CGPA Cutoff: 7.00

Branches: CSE/ECE/EE (B. Tech and Dual Degree)

No. of students taken: 2

About the Interview

Procedure

1. PPT
2. Interview



Applied Materials

Placement

Job title: Application Engineer(AE) / Technical Product Support Engineer (TPS)

CTC: For AE: INR 1,885,271 + 6000 USD Stock (Vesting cycle 4 Years)

For TPS: INR 1,419,021 + 6000 USD Stock (Vesting cycle 4 Years)

CGPA Cutoff: 7.00

Branches: Dual Degree in (Electrical Engineering/ Mechanical Engineering/ Materials & Metallurgy/ Manufacturing Engineering)

No. of students taken: 2 + 1 (Respectively for AE and TPS)

About the Interview

Procedure

1. PPT
2. Online Test
3. Interview

Placement

Job title: Management Trainee

CTC: INR 20.1 LPA

CGPA Cutoff: 7.00 (Gen and OBC), 6.00 (sc/ST/PwD)

Branches: ME/CE/EE/CSE (B. Tech)

No. of students taken: 10

About the Interview

Procedure

1. PPT
2. Online Test
3. Interview

Browserstack



Placement

Job title: Software Engineer: Backend

CTC: INR 15 LPA

CGPA Cutoff: 8.00

Branches: CSE (B. Tech)

No. of students taken: 2

About the Interview

Procedure

1. Shortlist from Resumes
2. Written Test
3. OT
4. Personal Interview

Placement

Job title: Associate Engineer

Job Desc: [Click here](#)

CTC: INR 14.89 LPA

CGPA Cutoff: 6.50

Branches: ME (Dual Degree and M. Tech)

No. of students taken: 2

About the Interview

Procedure

- 1.OT
- 2.Personal Interview
- 3.Group Discussion

Placement

Job title: Senior member of technical staff

CTC: INR 7-10 LPA

CGPA Cutoff: 6.00

Branches: CE (Dual Degree and M. Tech)

No. of students taken: 5

About the Interview

Procedure

- 1.2 tests
2. Interviews (HR & Director round)



Placement

Job title: Junior Engineer – Full Stack Developer

CTC: INR 12 LPA

CGPA Cutoff: 6.00

Branches: Open to all

No. of students taken: 1

About the Interview

Procedure

- 1.OT
- 2.Personal Interview
- 3.Group Discussion
- 4.Written Test



Cubastion

Placement

Job title: Graduate Trainee Engineer

CTC: INR 9.61 LPA

CGPA Cutoff: 6.00

Branches: Open to all

No. of students taken: 1

About the Interview

Procedure

- 1.OT
- 2.Personal Interview
- 3.Group Discussion
- 4.Written Test

Placement

Job title: Structural Engineer

CTC: INR 6.1 LPA

CGPA Cutoff: 8.00

Branches: ECE/EE/ME/CE (B. Tech), ECE/EE/ME/CST (M. Tech)

No. of students taken: 2

About the Interview

Procedure

1. Shortlist from Resumes
2. Personal Interviews



Datoms

Placement

Job title: Full stack developer

CTC: INR 13.61 LPA

CGPA Cutoff: 7.00

Branches: All Branches (B. Tech)

No. of students taken: 2

About the Interview

Procedure

1. Shortlist from Resumes
2. Personal Interviews

Placement

Job title: Machine Learning Engineer I

CTC: INR 19 LPA

CGPA Cutoff: 6.50

Branches: Circuital branches (B. Tech/Dual Degree/M. Tech)

No. of students taken: 1

About the Interview

Procedure

1. Shortlist from Resumes
2. Personal Interviews

Futures First



Placement

Job title: Trainee – International Markets

CTC: INR 13.38 LPA

CGPA Cutoff: 7.00

Branches: All branches (B. Tech/Dual Degree/M. Tech)

No. of students taken: 1

About the Interview

Procedure

1. Shortlist from Resumes
2. Personal Interviews

Placement

Job title: Assistant Manager

CTC: INR 8 LPA

CGPA Cutoff: 7.00

Branches: Environment, IT, Mines, Civil, Electrical, Mechanical, Geology(M.Sc)

No. of students taken: 3

About the Interview

Procedure

1. Personal Interviews

Google



Placement

Job title: Full Time Software Engineer

CTC: INR 58.48 LPA

CGPA Cutoff: 7.50

Branches: CSE/ECE/EE

No. of students taken: 4

About the Interview

Procedure

1. Shortlisting through resumes
2. A technical 60-minute Google Online Challenge
3. 3-4 technical interviews of 45 minutes each



Placement

Job title: Officer – Engineering

CTC: INR 17.41 LPA

CGPA Cutoff: 6.00 (Gen/OBC), 5.00 (SC/ST/PwD)

Branches: EE (B. Tech)

No. of students taken: 3

About the Interview

Procedure

1. Shortlisting based on details filled in Google Form



Placement

Job title: SDE

CTC: 16LPA(BTech), 17LPA(MTech)

CGPA Cutoff: 7.50

Branches: (CSE/ECE/EE)

No. of students taken: 2

About the Interview

Procedure

1. Shortlist of resumes
2. Written Test
3. Interview - one technical, one HR round



Placement

Job title: Engineer, GET, PGET

CTC: 8LPA (BTech), 8.15LPA (MTech)

CGPA Cutoff: 5.00

Branches: ME

No. of students taken: 2

About the Interview

Procedure

1. Shortlist of resumes
2. Written Test
3. GD
4. Personal Interview

Placement

Job title: Engineer, GET, PGET

CTC: 8LPA (BTech), 8.15LPA (MTech)

CGPA Cutoff: 5.00

Branches: ME

No. of students taken: 4

About the Interview

Procedure

1. Shortlist of resumes
2. Written Test
3. GD
4. Personal Interview



Placement

Job title: Academic Manager

CTC: 7.5LPA

CGPA Cutoff: 6.00

Branches: All

No. of students taken: 14

About the Interview

Procedure

1. Shortlist of resumes
2. Written Test
3. Personal Interview

Placement

Job title: PGET Trainee

CTC: 8.5LPA

CGPA Cutoff: 6.00

Branches: All

No. of students taken: 2

About the Interview

Procedure

1. Shortlist of resumes
2. Written Test
3. Personal Interview



Placement

Job title: GET, PGET

CTC: GET - 6LPA (office based posting)

- 6.57LPA (job site posting)

PGET - 6.25LPA (office based posting)

- 6.80LPA (job site posting)

CGPA Cutoff: 6.00

Branches: All

No. of students taken: 7

About the Interview

Procedure

1. Online Test
2. Personal Interview(including extempore)



Placement

Job title: Digital Twin Engineer

CTC: 9.5LPA

CGPA Cutoff: 6.00

Branches: All

No. of students taken: 2

About the Interview

Procedure

1. Online Test
2. Personal Interview(including extempore)

Placement

Job title: Associate Hardware Engineer

CTC: 10.4LPA

CGPA Cutoff: 7.00

Branches: ECE

No. of students taken: 1

About the Interview

Skills

1. Intern/project in PCB, test equipment, VLSI, circuit design, electrical theory

Placement

Job title: SE 1

CTC: 13LPA

CGPA Cutoff: 6.00

Branches: CSE

No. of students taken: 3

About the Interview

Procedure

1. Online test
2. Personal interview

Placement

Job title: Business Analyst

CTC: 21LPA, 13 fixed

CGPA Cutoff: NA

Branches: All

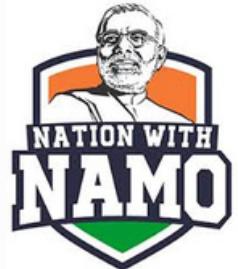
No. of students taken: 4

About the Interview

Procedure

1. Online test
2. Personal interview

Nation with Namo



Placement

Job title: Decision Scientist

CTC: 10.2LPA

CGPA Cutoff: NA

Branches: All

No. of students taken: 1

About the Interview

Procedure

1. Online test
2. Personal interview

Skills:

1. System Preparation and Output Generation
2. Research and Statistical Model Development
3. Data Analysis and Reporting
4. Cross-Functional Collaboration
5. Data Custodianship

Placement

Job title: Engineer Involved in IT Innovation Using the Latest IT Technologies, In-house SE for IT infrastructure (Infrastructure Engineer)

CTC: 2,928,000JPY

CGPA Cutoff: NA

Branches: All

No. of students taken: 2

About the Interview

Procedure

1. Resume shortlist
2. Online test
3. Written test
4. Personal interview

Nvidia

Placement

Job title: 6 Month Software Engineering Intern

Stipend: INR 80,000 /Month

CGPA Cutoff: 4.00

Branches: CSE/ECE/EE

No. of students taken: 1

About the Interview

Procedure

1. Resume shortlist
2. Online Test
3. Personal interview

OneFin

Placement

Job title: SDE 1 (backend)

CTC: 16LPA

CGPA Cutoff: 8.00

Branches: CSE(BTech)

No. of students taken: 3

About the Interview

Skills

1. Proficiency in Python, with a solid understanding of Django, Celery, and Redis.
2. Strong understanding of backend best practices and architecture.
3. Experience with AWS or other cloud services.
4. Troubleshoot and debug applications.

Selection Procedure

1. Aptitude test and email writing round
2. Students who clear (1) will be undergoing a couple of in-person technical and quantitative interviews
3. Students who clear (2) will be undergoing HR round

OneFin

Placement

Job title: DevOps Engineer

CTC: 16LPA

CGPA Cutoff: 8.00

Branches: CSE(BTech)

No. of students taken: 3

About the Interview

Skills

1. Proficiency in AWS cloud services (ECS, S3, EC2, RDS, etc.) and Python scripting for automation.
2. Hands-on experience with Docker, container orchestration (ECS), and infrastructure as code (CloudFormation, Terraform).
3. Infrastructure as code (CloudFormation, Terraform)
4. Solid knowledge of networking, security protocols, and best practices.

Selection Procedure

1. Aptitude test and email writing round
2. Students who clear (1) will be undergoing a couple of in-person technical and quantitative interviews
3. Students who clear (2) will be undergoing HR round

OneFin

Placement

Job title: ML Engineer

CTC: 16LPA

CGPA Cutoff: 8.00

Branches: CSE(BTech)

No. of students taken: 3

About the Interview

Skills

1. Strong programming skills in Python, R, or similar languages.
2. Solid understanding of statistics, probability, and algorithms.
3. Strong analytical skills to quickly understand business problems, formulate them as mathematical problems and suggest quantitative solutions to those problems.
4. Experience in analyzing large amounts of data. Ability to develop, test and validate hypotheses to take modeling decisions based on the data.

Selection Procedure

1. Aptitude test and email writing round
2. Students who clear (1) will be undergoing a couple of in-person technical and quantitative interviews
3. Students who clear (2) will be undergoing HR round

Placement

Job title: Graduate Engineer Trainee

CTC: 4LPA(during training), 8 or 10 LPA after training

CGPA Cutoff: 7.00

Branches: All

No. of students taken: 3

About the Interview

Skills

1. Develop moderately complex software in C#, .Net, Java, Mobile (iOS, Android), or develop cutting edge Data Warehousing & Business Intelligence applications.
2. Create and execute designs for small sets of new functionalities as part of a software project.
3. Perform technical root cause analysis and outlines corrective action for given problems.
4. Familiarity with software development tools like Git, JIRA and Agile methodologies.

Selection Procedure

- 1.Aptitude test and email writing round
- 2.Students who clear (1) will be undergoing a couple of in-person technical and quantitative interviews
- 3.Students who clear (2) will be undergoing HR round



Placement

Job title: Trainee faculty

CTC: 6.5LPA

CGPA Cutoff: 6.00

Branches: All

No. of students taken: 3

About the Interview

Requirements

1. Passion for teaching
2. Deep subject matter expertise
3. Natural mentorship abilities

Selection Procedure

1. Resume shortlist
2. Written test
3. Online test



Placement

Job title: PDE 1

CTC: 11.24 – 15PA

CGPA Cutoff: 8.00

Branches: CSE(BTech)

No. of students taken: 4

About the Interview

Skills

1. Basic understanding of software development principles and system design.
2. Familiarity with programming languages (e.g., Java, Python, JavaScript, Machine Learning) and tools is a plus.
3. Experience with third-party integrations or APIs is a bonus but not required.

Selection Procedure

1. Pen and paper assessment
2. Virtual interview

Placement

Job title: R&D Engineer Trainee(Embedded Software)

CTC: 9.33LPA

CGPA Cutoff: 8.00

Branches: CSE/EE/ECE

No. of students taken: 2

About the Interview

Skills

Seeking Highly motivated individuals with strong problem-solving skills, a passion for learning new technologies, and knowledge of C/C++, Linux, RTOS, DSP Processor Development, Cross-compilation, OS – Linux/Windows for a unique program aimed at providing future employment opportunities.

Selection Procedure

1. Skill set assessment
2. Technical assessment
3. HR round

Placement

Job title: R&D Engineer Trainee(FPGA/DSP)

CTC: 9.33LPA

CGPA Cutoff: 8.00

Branches: EE/ECE

No. of students taken: 2

About the Interview

Skills

Seeking Highly motivated individuals with strong problem-solving skills, a passion for learning new technologies, and knowledge of digital electronics, VHDL/Verilog, DSP, and FPGA design for a unique program aimed at providing future employment opportunities.

Selection Procedure

1. Skill set assessment
2. Technical assessment
3. HR round

Quicksell



Placement

Job title: Android Developer, AI Engineer

CTC: Android Developer – 18 LPA, AI Engineer – 36 LPA

CGPA Cutoff: NA

Branches: EE/ECE

No. of students taken: 1

About the Interview

Skills

https://drive.google.com/drive/folders/1qGH-0IJ4aiaf3380i7GUJZXqfxaarFEk?usp=share_link

Selection Procedure

1. Online assessment
2. Technical interview
3. HOD interview
4. Founder interview

Rhythm Innovations



Placement

Job title: Business analyst, development

CTC: 5LPA

CGPA Cutoff: 7.50

Branches: CSE/ECE

No. of students taken: 4

About the Interview

Selection Procedure

1. MCQ Test
2. Design test
3. 2 interviews
4. HR round

RELIANCE



Placement

Job title: Graduate Engineer Trainee

CTC: 9 LPA

CGPA Cutoff: 7.00

Branches: All

No. of students taken: 10

About the Interview

Selection Procedure

1. Aptitude test
2. Subject matter test
3. Personal interview

Placement

Job title: AI Engineer

CTC: 12 LPA

CGPA Cutoff: 7.00

Branches: B. Tech, Dual Degree, M. Sc. (All branches)

No. of students taken: 1

About the Interview

Selection Procedure

1. Shortlist from resumes
2. Written test
3. Personal Interviews

Placement

Job title: Research Engineer – 1

CTC: 10.5 LPA

CGPA Cutoff: 8.00

Branches: Materials Science/ Mechanical/Civil (Dual Degree and M. Tech)

No. of students taken: 2

About the Interview

Selection Procedure

1. Shortlist from resumes
2. Written test
3. Personal Interviews

Samsung R & I



Placement

Job title: Android Developer, AI Engineer

CTC: 21.5 LPA

CGPA Cutoff: 7.50

Branches: CSE/ECE (B.Tech and Dual Degree)

No. of students taken: 2

About the Interview

Selection Procedure

1. Online assessment
2. Personal Interviews

Placement

Job title: Associate Developer

CTC: 14.25 LPA

CGPA Cutoff: 6.00

Branches: CSE/ECE (B.Tech and Dual Degree)

No. of students taken: 4

About the Interview

Selection Procedure

1. Resume Shortlisting
2. Online Test
3. Technical Interview
4. Manager + HR Interview

Placement

Job title: Data Science Trainee/ SDE Trainee

CTC: 10 LPA (Both roles)

CGPA Cutoff: 7.00 (Both roles)

Branches: All Branches (B. Tech/Dual): Data Science Trainee

CSE/ECE/EE (B. Tech/Dual): SDE Trainee

No. of students taken: 13 total: 9 (Data Science) + 4 (SDE Trainee)

About the Interview

Selection Procedure

1. Resume Shortlisting
2. Online Test
3. Technical Interview
4. Manager + HR Interview

Sri Chaitanya



Placement

Job title: Assistant Lecturer; Counsellor

Job Desc:

https://drive.google.com/file/d/13KUKSILh9uGoNZmnUOrrMISHu_ufYjhP/view?usp=drive_link

CTC: 7 LPA (Assistant Lecturer); 4.5 LPA (Counsellor)

CGPA Cutoff: 6.00

Branches: All BTech and DD Branches

No. of students taken: 3

About the Selection

Skills

- Traits include responsibility, diligence, and conscientiousness.
- Strong communication skills.
- Commitment to professional growth.
- Interest in the teaching and education fields.
- Full-time position requiring residency on campus throughout the program.

Placement

Job title: IT

Job Desc:

https://drive.google.com/file/d/13KUKSILh9uGoNZmnUOrrMISHu_ufYjhP/view?usp=drive_link

CTC: 21 LPA

CGPA Cutoff: 7.00

Branches: BTech and DD CSE

No. of students taken: 3

About the Selection

Skills

- Work and develop expertise on a Digital Lending Platform
- Be the owner of the Loan Origination, Servicing, Debt Management, and surrounding
- IT systems.
- Ensure smooth business operations by ensuring continual availability of the IT systems
- Identify opportunities for continual improvement
- Work with Incident Lending Software FinnOne Neo, Management Tool Helix,
- Collaboration Tool MS Teams
- Work collaboratively with business users, business partners, and IT Team members.
- Attend meeting with business, understand business expectations, and resolve
- business queries

Placement

Job title: Data Scientist; Cloud Engineer/Architect; AI Engineer; Microservices Engineer; DevSecOps Engineer

Job Desc:

https://drive.google.com/file/d/13KUKSILh9uGoNZmnUOrrMISHu_ufYjhP/view?usp=drive_link

CTC: 9.08 LPA

CGPA Cutoff: 6.00

Branches: All BTech and DD

No. of students taken: 1

About the Selection

TCS Assessment follows:

1. Section 1 - Verbal Ability (20 mins)
2. Section 2 - Advanced Quantitative Aptitude (30 mins)
3. Section 3 - Advanced Coding (70 mins)



Placement

Job title: Jr. BIM Engineer

CTC: 5.5 LPA

CGPA Cutoff: 6.00

Branches: BTech and DD EE, ME, CE branches

No. of students taken: 3

About the Selection

1. Pre-Placement Talk
2. Written Test (Technical and Aptitude)
3. Online Test
4. Interview

Placement

Job title: Sales Engineer

CTC: 11 LPA

CGPA Cutoff: 7.00

Branches: All BTech and DD branches

No. of students taken: 3

About the Selection

- 1.Resume Shortlisting
- 2.Personal Interview

Placement

Job title: Data Analyst

CTC: INR 13 LPA

CGPA Cutoff: 6.50

Branches: All BTech and DD branches

No. of students taken: 17

About the Selection

1. **Round 1:** Profile Screening
2. **Round 2:** Online Test
3. **Round 3:** Two Technical Discussions
4. **Round 4:** HR Discussion

Skills required

- Proficient in Programming – Python/C/C++
- Strong verbal and written communication
- BE / B. Tech from a CS/IT/Circuit stream is mandatory



Placement

Job title: Data Analyst

CTC: INR 10 LPA

CGPA Cutoff: 7.00

Branches: All BTech and DD branches

No. of students taken: 3

About the Selection

1. Pre-Placement Talk
2. Written Test (Technical and Aptitude)
3. Online Test
4. Interview

Skills required

- Technical Competency: Strong technical skills for effective delivery.
- Commitment & Ownership: Willingness to take on larger responsibilities.
- Flexibility & Adaptability: Ability to adapt to our culture and evolving roles due to emerging technologies and client needs.
- Communication: Effective interaction with teams and clients, and developing skills for creating visual aids.



Placement

Job title: Associate Software Developer

CTC: INR 7 LPA

CGPA Cutoff: 7.00

Branches: All BTech and DD branches

No. of students taken: 3

About the Selection

1. Pre-Placement Talk
2. Written Test (Technical and Aptitude)
3. Online Test
4. Interview

Turing



Placement

Job title: Data Scientist; Business Analyst

CTC: 13 LPA; 9 LPA

CGPA Cutoff: 6.00 (DS role); 7.00 (BA role)

Branches: All BTech and DD branches

No. of students taken: 7 as Data Scientist; 2 as Business Analyst

About the Selection

1. Pre-Placement Talk
2. Written Test (Technical and Aptitude)
3. Online Test
 - Data Scientist role - Aptitude, Python and Written Test
 - Business Analyst - Aptitude and Written Test

Skills required:

Data Analyst

- Evaluate and rank AI model responses based on user requests across a wide range of CS topics, providing detailed rationales for your decisions.
- Craft perfect responses and explain your reasoning and logic comprehensively for your actions. Conduct peer code reviews

Business Analyst

- Analytical Skills: Good research and analytical skills
- Feedback Skills: Ability to provide constructive feedback and detailed annotations.
- Creative Thinking: Creative and lateral thinking abilities.

Placement

Job title: Software Engineer

CTC: 21.6 LPA

CGPA Cutoff: 7.00

Branches: BTech and DD CSE and EE

No. of students taken: 4

About the Selection

1. Online Test
2. Interview

Skills required:

- Familiarity with software development tools and methodologies, such as version control systems (Git), integrated development environments (IDEs), and agile practices.
- Basic understanding of web technologies, databases, and cloud services.
- High ownership and accountability mindset



Placement

Job title: Graduate Engineer Trainee

CTC: INR 7 LPA

CGPA Cutoff: 7.00

Branches: ALL BTech and DD branches

No. of students taken: 2

About the Selection

1. Resume Shortlisting
2. Personal Interview

Placement

Job title: Software Engineer

CTC: INR 10 Lakhs fixed + 2 Lakhs Retention Bonus

CGPA Cutoff: 7.00

Branches: ALL BTech and DD branches

No. of students taken: 3

About the Selection

1. Pre-Placement Talk
2. Online Test
3. Interview

Skills required

Programming Languages: Python, Javascript, HTML, CSS, SQL

Databases: Snowflake/ MySQL / Oracle/ PostgreSQL/ Redshift

Data Science & Miscellaneous Technologies: A/B testing, ETL, Pandas, Spark, Sklearn, SciPy, Matplotlib, NLTK, Pytorch, Keras, Tensorflow, Time series, hypothesis testing, Topic Modeling and Deep Learning, Supervised Learning, Unsupervised Learning, Reinforcement Learning, Natural Language, Neural Network, LLMs, Generative AI, Retrieval Augmented Generation (RAG), Reinforcement Learning, Langchain

Version Control & Devops: Git, GitLab, Bitbucket, Docker, Kubernetes, Airflow, MLflow

Cloud: AWS / GCP / Azur



Placement

Job title: Member of Technical Staff-Software Engineer

CTC: INR 12L PA+1LPA (Joining Bonus one time) = 13LPA

CGPA Cutoff: 7.00

Branches: ALL BTech and DD branches

No. of students taken: 2

About the Selection

1. Written Test
2. Online Test
3. Interview

Placement

Job title: Software Development Engineer;
Product Analyst

CTC: INR 56 LPA; INR 21 LPA

CGPA Cutoff: 7.00

Branches: ALL BTech and DD branches

No. of students taken: 4

About the Selection

1. Pre-Placement Talk
2. Written Test (Technical and Aptitude)
3. Online Test
4. Interview



Placement

Job title: Decision Analytics Associate (DAA);
Business Technology Solutions Associate (BTSA)

CTC: INR 13,65,600/- per year

CGPA Cutoff: 7.00

Branches: ALL BTech and DD branches; CSE, EE, ECE

No. of students taken: 32

About the Selection

Phase 1

1. Pre-Placement Talk
2. Online Aptitude Test – analytical ability, structured and unstructured problem-solving skills
3. Communication Test – Speak on a topic for 60s

Phase 2

1. Interview Round 1
 - DAA Case Study Assessment – Two Business case solving
 - BTSA Tech Assessment – SQL, coding, programming and query writing and associated competencies
2. Interview Round 2
 - Questions on Resume, brain teasers, guesstimates, puzzles



Placement

Job title: Data Science Associate (DSA)

CTC: INR 19,00,000/- per year

CGPA Cutoff: 7.00

Branches: ALL BTech and DD branches

No. of students taken: 32

About the Selection

Online Test:

MCQ & Programming (130 mins): Includes MCQs on Machine Learning, Statistics, Applied Mathematics, and Aptitude, along with a Python programming section. Be mindful of negative marking.

Corporate Communication Test (60 mins): Evaluates written communication skills, structure, and clarity.

ML Case Study (75 mins): Involves solving a real-world machine learning problem. You'll need to justify your solution with code, methodology, key steps, results, and recommendations.

Technical Interview:

Be prepared to present a project that showcases your data science skills. Clearly explain the problem, approach, methodology, and outcomes. Expect questions on the online test problems, and be ready to discuss a new business problem, framing your approach and possible tech stack.

EBC Interview:

This round focuses on your past experiences and understanding of data science concepts. Discuss relevant projects in depth and demonstrate your problem-solving mindset.



Campus M.Tech. Placements

2024-25

PG Placement

Job title: Post Graduate Engineer Trainee

Job Desc: Civil Core (Technical)

CTC: 4.8 INR LPA

CGPA Cutoff: 60% throughout academics (No active backlogs)

Branches: Water Resources, Urban Planning, Transport Planning, Power Electronics & Drives, Geoinformatics, Construction Management, Structural Engineering, Transportation Engineering, Environmental Engineering, Geotechnical M.Arch

No. of Students taken: 1

About the Interview

Procedure

1. Written Test (Aptitude & Technical)
2. Group Discussion/JAM
3. Two Rounds of Interviews

PG Placement

Job title: Software Engineer / 5G Communication System
Engineer / Design Engineer

CTC: 26 LPA

CGPA Cutoff: 7.00

Branches: CSE/ ECE/ EE

No. of Students taken: 1

About the Interview

Procedure

1. Shortlist from Resumes:
2. Written Test (Technical, Aptitude)
3. Personal Interview
4. PPT

PG Placement

Job title: Application Engineer/ Technical Product Support (TPS) Engineer

CTC: 18 LPA

CGPA Cutoff: 7.00 & no current arrears

Branches: (Electrical Engineering/ Mechanical Engineer/ Materials & Metallurgy/Manufacturing Engineering)

No. of Students taken: 1

About the Interview

Procedure

1. Personal Interview
2. Online Test
3. PPT

PG Placement

Job title: Post Graduate Engineer

CTC: 6.75 LPA & Rs. 20,000/- per month (stipend- Internship)

CGPA Cutoff: 7.00

Branches: Civil , Electrical, MechanicalMaster-Urban Planning ,
Master Construction Management , M.Tech- Architecture ,
M.Tech-Transportation

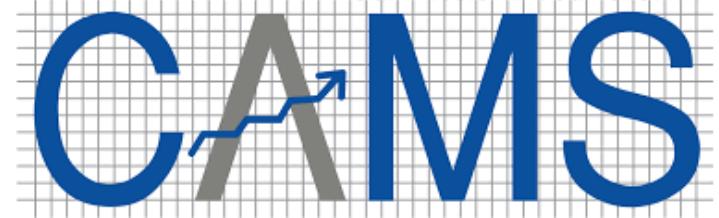
No. of Students taken: 6

About the Interview

Procedure

1. Online Assessment
2. Group Discussion
3. Technical Interview
4. HR Interview

CAMS



PG Placement

Job title: Software Development Engineer

CTC: 10 LPA

CGPA Cutoff: 7.00

Branches: CSE

No. of Students taken: 2

About the Interview

Procedure

1. Written Test (Technical, Aptitude)
2. Personal Interview
3. PPT

PG Placement

Job title: Senior member of technical staff/ Subject matter expert/ Product definition engineer/ Technical sales service

CTC: 7 to 10 LPA

CGPA Cutoff: 6.00

Branches: CE (Dual degree & M.tech)

No. of Students taken: 4

About the Interview

Procedure

1. 2 tests
2. Interviews (HR & Director round)



PG Placement

Job title: Assistant Lecturer

CTC: 7.5–8.5 LPA

CGPA Cutoff: 6.00

Branches: (CSE/ECE/EE/ME/CE/MM/CST)

No. of Students taken: 2

About the Interview

Procedure

1. WRITTEN TEST
2. TECHNICAL
3. HR ROUND

PG Placement

Job title: Structural Design Engineer, Electrical/Telecom
Engineer, Mechanical Engineer

CTC: 6 LPA

CGPA Cutoff: 7.00

Branches: (CSE/ECE/EE/ME/CE/MM/CST)

No. of Students taken: 7

About the Interview

Procedure

1. Written Test (Technical, Aptitude)
2. Group Discussion
3. Online Test
4. PPT

Gujarat Mineral Development Corporation



PG Placement

Job title: Assistant Manager-Mining/ Surveyor / Environment /Geology

CTC: 6-8 LPA

CGPA Cutoff: 7.00

Branches: CSE/ECE/EE/ME/CE/MM/CST

No. of Students taken: 1

About the Interview

Procedure

1. Shortlist from Resumes
2. Personal Interview
3. PPT

PG Placement

Job title: Technical Lead-Machine Learning Engineer/Imaging/Computer Vision

CTC: 10 LPA

CGPA Cutoff: 60% throughout the academics

Branches: Computer Science /IT only

No. of Students taken: 3

About the Interview

Procedure

1. Registration on our Careers Portal (Link is mentioned above)
2. Profile/Resume Shortlisting
3. Online Test
4. Technical Interview 1 and 2
5. HR Interview (if shortlisted in Technical Interview)

PG Placement

Job title: Software Development Engineer

CTC: 17 LPA

CGPA Cutoff: : 7.50

Branches: CSE/ECE/EE

No. of Students taken: 1

About the Interview

Procedure

1. Shortlist from Resumes
2. Written Test(Technical, Aptitude)
3. Personal Interview -1 round of Technical and 1 round of Behavioral Interview
4. PPT

PG Placement

Job title: PGET/GET

Job Desc: Core(Technical)

CTC: 6 LPA

CGPA Cutoff: min 6.50 , 65% in HSC & SSC

Branches: CSE/ECE/EE/ME/CE

No. of Students taken: 1

About the Interview

Procedure

1. Shortlist from Resumes
2. Personal Interview
3. Online Test
4. PPT



PG Internship

Job title: Hardware Engineering Intern

CTC: INR 80,000 per month (6 month duration)

CGPA Cutoff: 7.80

Branches: ECE, EEE, EE, CSE (core), VLSI, Microelectronics

No. of Students taken: 2

About the Interview

Procedure

1. Mix of Aptitude and Technical (Online)
2. 1 round of technical panel interview

SKILLS

Computer Architecture, Digital Design Fundamentals, Puzzles, Analytical & Problem Solving, Coding, VLSI

PG Placement

Job title: Research Engineer – 1

Job Desc: Research and Development

CTC: 9.45-10.5 LPA

CGPA Cutoff: 8.00 CGPA in BTech and MTech

Branches: CSE/ECE/EE/ME/CE/MM/CST/Materials Science

No. of Students taken: 3

About the Interview

Procedure

1. Shortlist from Resumes
2. Written Test case study and aptitude
3. Personal Interview
4. Online Test
5. PPT

PG Placement

Job title: R&D Engineer

CTC: INR 21.5 Lacs

CGPA Cutoff: 7.50

Branches: CSE/ECE/CST

No. of Students taken: 1

About the Interview

Procedure

1. Personal Interview
2. Online Test

PG Placement

Job title: Master Engineer Trainee (MET)

CTC: INR 12.5 LPA/ INR 35,000 per month (Stipend- Internship)

CGPA Cutoff: Should have 65% and above in X, XII, Graduation and Post-Graduation

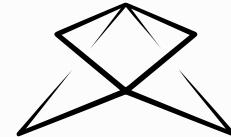
Branches: Electronics and Communication , Electrical , Power Electronics , Power Systems, Embedded Systems ,Control Systems, Mechanical, Machine Design, Mechatronics/Industrial Automation & Robotics

No. of Students taken: 2

About the Interview

Procedure

1. Resume Shortlisting
2. Online Assessment
3. Personal Interview



PG Placement

Job title: Post Graduate Engineer

CTC: INR.6 – 10 LPA / INR 20K (internship stipend)

CGPA Cutoff: 7.00

Branches: Civil , Mechanical & Electrical

No. of Students taken: 2 (1 intern + 1 placed)

About the Interview

Procedure

- 1.Resume Shortlisting
- 2.Online Assessment
- 3.Personal Interview



PG Placement

Job title: Trainee Design Engineer – Transportation/Structures

CTC: Rs. 8 LPA

CGPA Cutoff: 7.00

Branches: CE

No. of Students taken: 2

About the Interview

Procedure

1. Shortlist from Resumes
2. Personal Interview
3. Online Test
4. PPT

Switch Mobility

SWITCH

PG Placement

Job title: Service Engineer

Job Desc: CTC: 5 LPA gross during first year (training year),
7.5 LPA from second year onwards.

CGPA Cutoff: 7.00 from 10th onwards

Branches: M.Tech in ME, EEE, ECE, Power Electronics, IT

No. of Students taken: 2

About the Interview

Procedure

1. OT, Interviews

PG Placement

Job title: Analog Design Engineer / R&D Engineering, Sr Engineer / HIGH-SPEED SERDES PHY team COSIM profile

Job Desc: [Click Here](#)

CTC: 21,78,584 INR

CGPA Cutoff: 7.00

Branches: CSE, EE, ECE

No. of Students taken: 2

About the Interview

Procedure

1. Resume Shortlisting
2. Online Assessment
3. Personal Interview

PG Placement

Job title: Engineer Trainee

CTC: Rs. 5.0 LPA (fixed)

CGPA Cutoff: : 60% and above (10th, 12th, Bachelors). 60% in every semester of PG

Branches: Mechanical all specialization (Machine Design preferred) & Electrical all specialization (Power System, Power electronics preferred), Architecture

No. of Students taken: 1

About the Interview

Procedure

1. Online Test
2. Technical Round
3. Video Screening Round
4. HR Round/Pre-Medicals

Skills needed: Good knowledge in Technical concepts & Good communication skills

PG Placement

Job title: Data Scientist; Cloud Engineer/Architect; Engineer(Digital Transformation, Cloud and Artificial Intelligence);

CTC: 11.58 LPA

CGPA Cutoff: Minimum 60% or 6.00 CGPA

Branches: M Tech(CSE/EE)

No. of Students taken: 1

About the Interview

Procedure

1. Shortlist from Resumes
2. Personal Interview
3. PPT

PG Placement

Job title: Jr. BIM Engineer

CTC: 5-7LPA

CGPA Cutoff: : 6.50

Branches: EE/ME/CE

No. of Students taken: 1

About the Interview

Procedure

1. Written Test(Technical, Aptitude)
2. Online Test

PG Placement

Job title: Post Graduate Engineer Trainee

CTC: INR.6 to INR.10 LPA

CGPA Cutoff: 6.00

Branches: M. Tech/ M.E/PGP- Project Management/ Construction Management (PMO/ PM / CTM / CPM / CEM)/Infrastructure Management

No. of Students taken: 2

About the Interview

Procedure

- 1.Resume Shortlisting
- 2.Online Assessment
- 3.Personal Interviews



Campus
Pre Placements
Offers
2024-25

Placement

Job title: SDE

CTC: INR 30 LPA

Internship Stipend: INR 75,000

CGPA Cutoff: 7.00

Branches: CSE, EE, ME, CE, MM

No. of students taken: 2

About the Selection:

Hires primarily through internships which lead into Pre-Placement Offers

1. Resume Shortlist
2. Online Assessment
3. Personal Interviews



Placement

Job title: SDE

CTC: INR 67.6 LPA

Internship Stipend: INR 1,00,000

CGPA Cutoff: 7.00

Branches: CSE, EE, ECE (BTech), CSE, EE (Dual)

No. of students taken: 7

About the Selection:

Hires primarily through internships which lead into Pre-Placement Offers

1. Resume Shortlist
2. Online Assessment
3. Personal Interviews



Placement

Job title: SDE

CTC: INR 34.4 LPA

Internship Stipend: INR 1,00,000

CGPA Cutoff: 7.00

Branches: All

No. of students taken: 1

About the Selection:

Hires primarily through internships which lead into Pre-Placement Offers

1. Resume Shortlist
2. Online Assessment
3. Personal Interviews



Campus Extras 2024-25

Came for recruitment but left without
making a single offer

Placement

Job title: Graduate Engineer Trainee

CTC: INR 16 LPA

CGPA Cutoff: 7.00

Branches: All Branches (B. Tech + Dual Degree)

About the Interview

Procedure

1. Resume Shortlisting
2. Online Assessment
3. Personal Interviews



PG Placement

Job title: Early Career Progression

CTC: 8.5 LPA

CGPA Cutoff: 7.00

Branches: All Branches (M. Tech.)

About the Interview

Procedure

1. Resume Shortlisting
2. Online Assessment
3. Personal Interviews



Placement

Job title: Trainee Engineer

CTC: 21 LPA

CGPA Cutoff: 7.00

Branches: All Branches

About the Interview

Procedure

1. Resume Shortlisting
2. Online Assessment
3. Personal Interviews



3Month Internship with PPO

Job title: Software Developer Engineer Intern, Business Analyst

CTC: 12LPA, 10LPA

Internship Stipend: INR 35K per month

CGPA Cutoff: 7.00

Branches: CSE/ECE/EE

About the Interview

Procedure

- 1.Resume Shortlisting
- 2.Online Assessment
- 3.Personal Interviews

Ather Energy



Placement

Job title: Graduate Engineer Trainee Supply Chain

CTC: INR 12 LPA

CGPA Cutoff: 7.00

Branches: B. Tech/M. Tech (ME/EE/ECE)

About the Interview

Procedure

1. Resume Shortlisting
2. Online Assessment
3. Personal Interviews



PG Placement

Job title: Design Engineer

CTC: INR 8 LPA

CGPA Cutoff: 65% & Above from 10th Onwards

Branches: M. Tech. (ECE (Communication & Signal Processing/ RF and Microwave))

About the Interview

Procedure

1. Resume Shortlisting
2. Online Assessment
3. Personal Interviews

Functional Skills: (Mandatory) :

- Strong fundamentals in Signal Processing and its practical mapping to digital design.
- Hands-on experience in MATLAB Modelling Signal Processing Chain (Digital Communications, Satcom, EW, or RADAR).
- Working knowledge of FPGAs, Embedded Platforms.
- Proficiency in programming in HDL, C, Matlab.

Functional Skills: (Differentiator):

- Hands-on experience in FPGA Implementation of Signal Processing Chain (Digital Communications, Satcom, EW, or RADAR).
- Research or Project Work in the field of Signal Processing and Implementation using FPGAs or Embedded Software.
- Hands-on experience in working with AMD (Xilinx) FPGA/SoC Evaluation Platforms.
- Good knowledge of mathematics.



PG Placement

Job title: Assistant Manager

CTC: INR 12.42 LPA

CGPA Cutoff: 7.00

Branches: M. Tech/Dual Degree (EE/ECE)

About the Interview

Procedure

- 1.Resume Shortlisting
- 2.Online Interviews

Placement

Job title: Junior Software Engineer

CTC: INR 14 LPA

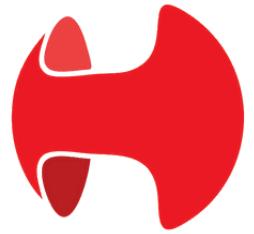
CGPA Cutoff: 7.00

Branches: B. Tech (CSE/ECE)

About the Interview

Procedure

1. Online Coding Test
2. Technical Interviews
3. HR Interview



Placement

Job title: IoT & Software Roles; Power Electronics & Engineering Design Roles

CTC: INR 20 LPA/19 LPA; INR 17 LPA/16 LPA

CGPA Cutoff: 6.50 (10th and Onwards)

Branches: B. Tech/ M.Tech (CSE/ECE/EE); M.Tech/PhD (EE/ECE)

About the Interview

Procedure

1. Online Test
2. Technical Personal Interview
3. HR Discussion



PG Placement

Job title: R&D Thermal Engineer

CTC: INR 10 LPA

CGPA Cutoff: 7.00

Branches: M. Tech (Power Electronics/ Power Systems)

About the Interview

Procedure

1. Resume Shortlisting
2. Online Test
3. Personal Interview

PG Placement

Job title: Engineering Analyst for Core (Turbo Machinery)

CTC: INR 9 -11 LPA

CGPA Cutoff: No Active Backlogs

Branches: M. Tech (ME)

About the Interview

Procedure

1. Resume Shortlisting
2. Online Test
3. Personal Interview



PG Placement

Job title: Design Engineer

CTC: INR 4.9 LPA

CGPA Cutoff: 6.00

Branches: M. Tech (Structural Engineering)

About the Interview

Procedure

1. Resume Shortlisting
2. Online Test
3. Personal Interview



PG Placement

Job title: Member of Technical Staff, Test & Validation

CTC: INR 19 LPA

CGPA Cutoff: 7.50

Branches: M. Tech (ECE)

About the Interview

Procedure

1. Resume Shortlisting
2. Online Test
3. Personal Interview

Money Forward



Placement

Job title: Software Engineer

CTC: 7,114,000 JPY

CGPA Cutoff: 7.00

Branches: All branches BTech, Dual, MTech

About the Interview

Procedure

1. Resume Shortlisting
2. Online Assessment
3. Personal Interviews

Tech Stack:

- Frontend: JavaScript/TypeScript
- Backend: Ruby/Go/Kotlin/Java/Python/Rust
- Mobile: Android (Kotlin/Java), iOS (Swift/Objective-C),
Cross Platform: Dart (Flutter)

Placement

Job title: Assistant Manager

CTC: 6 LPA

CGPA Cutoff: 6.00

Branches: MTech, BTech in Mechanical

About the Interview

Procedure

1. Resume Shortlisting
2. Written Assessment
3. Personal Interviews

Placement

Job title: Management Trainee

CTC: 10 LPA

CGPA Cutoff: 7.00

Branches: All branches BTech, Dual

About the Interview

Procedure

1. Assignment
2. Interview 1 – Head of ops
3. Interview 2 – COO, VP and HR



Tescra

Placement

Job title: Software Engineer

CTC: 15 LPA

CGPA Cutoff: 6.00

Branches: All branches BTech, Dual, MTech

About the Interview

Procedure

1. Resume Shortlisting
2. Online Assessment
3. Personal Interviews

Placement

Job title: Embedded software and hardware engineer

CTC: 6-9 LPA

CGPA Cutoff: 7.00

Branches: B. Tech, M. Tech, Dual Degree (EE)

About the Interview

Procedure

1. Resume Shortlisting
2. Online Assessment
3. Personal Interviews

List of Companies which visited for Internship Hiring in 2024-25

S.l No	Company Name	S.l No	Company Name	S.l No	Company Name
1	D.E. Shaw	18	Amazon	35	NavGurukul
2	Google	19	Jindal Stainless Ltd.	36	Vamshi Gudavarthi (Alumni)
3	Rippling	20	XRobotics	37	Factset
4	Nvidia	21	ABB	38	Midas Techfin Consultants
5	Tata Steel	22	Hanyaa Auto Technologies	39	Bentley Systems
6	Samsung RI	23	NHAI	40	Reliance Industries Ltd.
7	Media.Net	24	Zscaler	41	Karban Envirotech
8	Cisco	25	Lenovo	42	RIKA
9	Aarna	26	Aaartise Capital	43	Neophal
10	SarasAI	27	Hii Healthy	44	SmartOrbit
11	Jazzee Technologies	28	Bourntec Solutions	45	UltraTech
12	Atlassian	29	Inspecity Space Labs	46	Odissa State Pollution Control Board
13	Microsoft	30	Qualcomm	47	Mohs10 Technologies
14	Accenture	31	August AI	48	Vistora AI
15	FullToss	32	Bureau of Indian Standards	49	Bharat Digital
16	I'mBesideYou	33	AuroDigital Inc.	50	AlgoUniversity
17	QuantumStreet AI	34	eLogicTech Solutions India Ltd.	51	Counsello.ai

List of Companies which visited for Placements in 2024-25

S.I No	Company Name	S.I No	Company Name	S.I No	Company Name
1	50Hertz	26	CCTech	51	Infosys
2	Aaksh Institute	27	CISCO	52	Intercontinental consultants
3	Aarna	28	Cognizant	53	IPHIPI Technologies
4	Aarti Steel	29	Coreel	54	Ittiam Systems
5	Aarvee Associates	30	Cubastion	55	Jacob
6	Accenture India	31	Cuttack Agrovet	56	JEH Aerospace
7	Accenture Japan	32	Dar Al-Handasah	57	Jindal Stainless Limited
8	Accordion (Merilytics)	33	Datoms	58	JSPL
9	Addverb	34	Dayananda Sagar University	59	JW CONSULTANTS LLP
10	AECOM	35	DE Shaw	60	K12 Techno
11	AIRA Matrix	36	Delta Electronics	61	KEC International
12	Ananant Systems	37	Dolcera X	62	L&T Constructions
13	Applied Materials	38	EPAM	63	Lenovo
14	Apps For Bharat	39	FactSet	64	Leumas
15	AST Mobile	40	FuturesFirst	65	LTI Mindtree
16	Ather Energy	41	Garware Fiber Technical Fiber Ltd	66	Mahindra & Mahindra
17	Atkins	42	GMDC	67	MAQ Software
18	Bharat Electronics Limited	43	Goldman Sachs	68	Mathworks
19	Birla Pivot	44	Google	69	Mavenir
20	BiteSpeed	45	Havells India	70	MediaTek
21	BPCL (PSU)	46	HCL Technologies	71	Meesho
22	Browserstack	47	Hexware	72	Micron
23	C V Raman Academic	48	Hitachi Energy	73	Mihup
24	CAMS	49	HPCL (PSU)	74	Money Forward
25	Caterpillar	50	IndiaMart	75	mthree

List of Companies which visited for Placements in 2024-25

S.I No	Company Name	S.I No	Company Name	S.I No	Company Name
76	Nations with Namo	96	Samsung RI	116	Tescra
77	Niterra	97	Sapiens	117	Thriveni Earthmovers Pvt Ltd
78	Nvidia	98	Schneider electric	118	Tiger Analytics
79	Oil India Limited	99	SIEMENS	119	Tredence Analytics
80	OneFin	100	Sigmoid Analytics	120	Tudip Technologies
81	Oorjan	101	Skyroot	121	Turing
82	Oracle	102	SMC Industries	122	UKG
83	Oramae	103	Spectrum	123	Unacademy
84	PalTech	104	Sri Chaitanya	124	VA Tech Wabag
85	PayPal	105	SRM University	125	Vecmocon Technologies
86	Pentation Analytics	106	Switch Mobility	126	Vedanta
87	Phenom	107	SYNOPSYS	127	Volvo Eicher
88	Physics wallah	108	Tata Autocomp	128	WSP India
89	Qbit Labs	109	Tata Capital	129	Z Clap
90	QI Spine	110	Tata Steel	130	Zenshastra
91	Quicksell	111	TCE	131	ZL Technologies
92	Reliance Industries Ltd	112	TCS R&I	132	Zomato
93	Rhythm Innovations	113	Techfab Industries Ltd	133	ZS Associates
94	RoshAI	114	Tecture	134	Engineers India Limited
95	Saint Gobain	115	Tesa Tapes	135	MECON Limited

Disclaimer:

While preparing this handbook, some of the company names mentioned were included based on the information available at the time. In certain cases, complete details were not accessible during compilation. The information is intended solely for reference and may not fully reflect the final status of each company's recruitment process.



Credits

This handbook has been made possible through the dedicated efforts of the coordinators of the Career Development Cell. We would also like to extend our sincere gratitude to the student volunteers who generously contributed their knowledge, experiences, and time towards its creation.

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Student Internship Coordinator

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Student Internship Coordinator

Reddy Raghavendra

Krishnendu Bir

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CAREER DEVELOPMENT CELL

Where aspirations meet opportunities

Thank you for reading.

For any concerns, please reach out to
**Student Career Counselling
Coordinators** via:

 sccc.cdc@iitbbs.ac.in

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